

The 8th International Conference on Earthquake Geotechnical Engineering (8ICEGE)

Technical Exhibition Application Guidelines



Date: May 7 (Tue)– May 10 (Fri), 2024

Venue: Osaka International Convention Center

Hosted by the Japanese Geotechnical Society, and International Society for Soil Mechanics and Geotechnical Engineering, TC203 (Earthquake Geotechnical Engineering and associated problems)

Official conference web site : Search

or

<https://confit.atlas.jp/guide/event/icege8/static/outline>

Invitation

It is a great pleasure and an honor for us to extend a warm invitation to all of you to attend the 8th International Conference on Earthquake Geotechnical Engineering (8ICEGE) that will take place in Osaka, Japan, on 7-10 May, 2024.

Following the highly successful conferences of this series held in Tokyo 1995, Lisbon 1999, Berkeley 2004, Thessaloniki 2007, Santiago 2011, Christchurch 2015, and Roma 2019, the Japanese Geotechnical Society (JGS) on appointment by the ISSMGE Technical Committee 203 ('Earthquake Geotechnical Engineering and associated problems') is delighted to announce that Osaka will host the 8th International Conference on Earthquake Geotechnical Engineering (8ICEGE) from 7 to 10 in May 2024.

The 8ICEGE offers an outstanding technical program on a range of earthquake geotechnical engineering topics, which will be presented in the published proceedings as well as in the oral and poster sessions. We believe that the 8ICEGE will provide an excellent opportunity for earthquake and geotechnical engineers, geologists and seismologists, consulting engineers, public and private contractors, regional and national authorities, and all those involved in engineering projects and research related to earthquake geotechnical engineering, to exchange ideas and present their recent experience and developments. We hope that you will find the 8ICEGE professionally rewarding, scientifically stimulating, and personally enjoyable as were the previous ICEGEs.

Also, we would like to invite your organization or company to support the objectives of the upcoming 8ICEGE and to exhibit at the "Technical Exhibition Area". Please refer to this "Application Guidelines" for more information, and we look forward to seeing you at the booth. We would like to offer special benefits to sponsoring organizations and companies, as well as to devise ways to make the "technical exhibition" more effective.

There are always concerns nowadays about the COVID19 effects on conference organization. At this moment, the 8ICEGE intends to avoid virtual conference and provide participants with ample opportunities to meet and talk with each other and to visit technically interesting sites in and around Osaka.

Last but not least, as well as the central business hub in western Japan, Osaka has been at the heart of Japan's cultural and economic developments for hundreds of years with a perfect mix of traditional and modern cultures. The 8ICEGE will also provide you with a great opportunity to enjoy the many charms of Osaka.

Thank you for your participation and contributions in advance, and enjoy the conference and Osaka!

Misko Cubrinovski (TC203 Chair Person)

Junichi Koseki (JGS President)

Motoki Kazama (Chair Person of 8ICEGE Executive committee)

1. Outline of the event

Researchers and engineers from all over the world attend this quadrennial international conference. This is a unique opportunity for you to introduce your company's technology and deepen exchanges with the participants. Various sponsorship categories are available, so please consider applying.

Date: May 7 (Tue)– May 10 (Fri), 2024

Venue: Osaka International Convention Center (10F & 12F)

15-3-51, Nakanoshima Kita-ku, Osaka 530-0005 JAPAN

Tel : +81-6-4803-555

Website: <https://confit.atlas.jp/guide/event/icege8/static/outline>

Venue	Main venue	Sub-venue 1	Sub-venue 2	Sub-venue 3	Poster room	Technical Exhibition Hall	Reception/Lunch Venue
	Conference room 1001-1003	1009	1008	1202	1004-1007	10F & 12F Foyer	12F
	Opening and Closing Ceremonies, Oral Presentations and Keynotes	Oral presentation	Oral presentation	Oral presentation	Poster	Technical Exhibition	
7-May						Carry in	Reception
8-May	Opening ceremony	○	○	○	○	○	○
	○	○	○	○	○	○	
9-May	○	○	○	○	○	○	○
	○	○	○	○	○	○	
10-May	○	○	○	○	○	○	○
	Closing ceremony					Removal	

Host: Japanese Geotechnical Society, and International Society for Soil Mechanics and Geotechnical Engineering, TC203 (Earthquake Geotechnical Engineering and associated problems)

Expected number of participants: 700 participants from Japan and abroad (including 600 presenters)

Program Outline: Opening and Closing Ceremonies, Keynote Speech, General Abstracts (Oral and Poster Presentations), Welcome Reception, Banquet, Technical Tour, Accompanying Persons Program

Contact: Sponsor Office, 8th International Conference on Earthquake Geotechnical Engineering

E-mail: sponsor8icege@academicbrains.jp

Address: Tenma Chiyoda Build 2F-10, 1-1-1 Ishi-machi, Chuo-ku, Osaka, 540-0033, Japan

TEL: +81-6-6949-8137 FAX: +81-6-6949-8138

2. Sponsorship

Application period for sponsorship and exhibition: December 8, 2022 to January 31, 2024 (2nd call for applications: October 31, 2023)

Exhibition fee and privileges by sponsor category

Sponsors will be categorized into Platinum, Gold, Silver, Bronze, and Sapphire, and benefits will be offered according to each category. (Exhibition fee below is given by JPY=Japanese Yen)

	Platinum JPY1,000,000*	Gold JPY800,000*	Silver JPY500,000*	Bronze JPY300,000*	Sapphire JPY200,000*
Introduction as a sponsor company at the opening and closing ceremonies	○	-	-	-	-
Booth	Max. 2 booths	Max. 2 booths	Max. 2 booths	1 booth	-
Cyber exhibition on a special page on the official website	○	○	○	○	○
Logo placement on official website	○	○	○	○	○
Projection of advertisements (company name and organization name logo) on screens in lecture halls	○	○	○	○	○
Sponsor company signage during lunch/coffee	○	○	○	-	-
Conference pass	4	3	2	1	1
Banquet Invitation	3 Persons	2 persons	1 person	-	-
Advertisement page in the program book	1 page (color)	1/2page (color)	1/4page (B/W)	Company name only (B/W)	1/4page (B/W)
Logo placement on sponsor signage	○	○	○	○	○
Logo placement on conference bags	○	○	-	-	-
Flyers and novelties enclosed in conference bags	○	○	-	-	-
Priority allocation of booths in order of application*	◎	◎	◎	◎	-

*10% sales tax will be added.

Note) A conference pass is required to enter the conference venue. The required number of name badges will be issued only to enter the exhibition area.

◎ : The offer is valid for applications received by October 31, 2023.

*Please refer to the notes on page 7.

2.1 Platinum Sponsor: JPY1,000,000*

The following benefits will be provided.

- Introduction as a sponsor company at the opening and closing ceremonies
- Your company's exhibition booth at the venue (maximum of 2 booths)
- Cyber exhibition on a special page on the official website**
- Logo listing as a "Platinum Sponsor" on the official 8ICEGE website
- Display of your advertisement (company/organization name and logo) on the screen at the venue during breaks (all days)
- Introduction as a sponsor on a signboard during lunch and coffee service
- 4 Conference passes
- Invitation to the banquet for 3 persons
- One-page color advertisement in the 8ICEGE program book
- Your company logo on the sponsor's signboard to be placed at the venue on the day of the conference
- Logo on the conference bag
- Flyers and novelties in the conference bag

2.2 Gold Sponsor: JPY800,000*

The following benefits will be provided.

- Your company's exhibition booth at the venue (maximum 2 booths)
- Cyber exhibition on a special page on the official website**
- Logo listing as a "Gold Sponsor" on the official 8ICEGE website
- Display of your advertisement (company/organization name and logo) on the screen at the venue during breaks (all days)
- Introduction as a sponsor on a signboard during lunch and coffee service
- 3 Conference passes
- Invitation to the banquet for 2 persons
- 1/2-page color advertisement in the 8ICEGE program book
- Your company logo on the sponsor's signboard to be placed at the venue on the day of the conference
- Logo on the conference bag
- Flyers and novelties in the conference bag

2.3 Silver Sponsor: JPY500,000*

The following benefits will be provided.

- Your company's exhibition booth at the venue (maximum 2 booths)
- Cyber exhibition on a special page on the official website**
- Display of your advertisement (company/organization name and logo) on the screen at the venue during breaks (all days)
- Sponsor's name on a signboard during lunch and coffee service
- 2 Conference passes
- Invitation to the banquet for 1 person
- Logo listing as a "Silver Sponsor" on the official 8ICEGE website
- 1/4-page advertisement (black and white) in the 8ICEGE program book
- Your company logo on the sponsor's corporate signboard to be placed at the venue on the day of the conference

2.4 Bronze Sponsor: JPY300,000*

The following benefits will be provided

- Your company's exhibition booth at the venue (1 booth space)
- Cyber exhibition on a special page on the official website**
- Display of your advertisement (company/organization name and logo) on the screen at the venue during breaks (all days)
- 1 Conference pass
- Logo listing as "Bronze Sponsor" on the official 8ICEGE website
- Company name only in the 8ICEGE Program Book
- Your company logo on the sponsor's corporate signboard to be placed at the venue on the day of the conference

2.5 Sapphire Sponsor: JPY200,000*

The following benefits will be provided.

- Cyber exhibition on a special page on the official website**
- Display of your advertisement (company/organization name and logo) on the screen at the venue during breaks (all days)
- 1 Conference pass
- Logo listing as "Sapphire Sponsor" on the official 8ICEGE website
- 1/4-page advertisement (black and white) in the 8ICEGE program book
- Your company logo on the sponsor's corporate signboard to be placed at the venue on the day of the conference

*10% sales tax will be added.

** Example of cyber exhibition, please refer to the links below.

Search:

Or Visit <https://confit.atlas.jp/guide/event/icege8/static/ExibitonSponsorship>

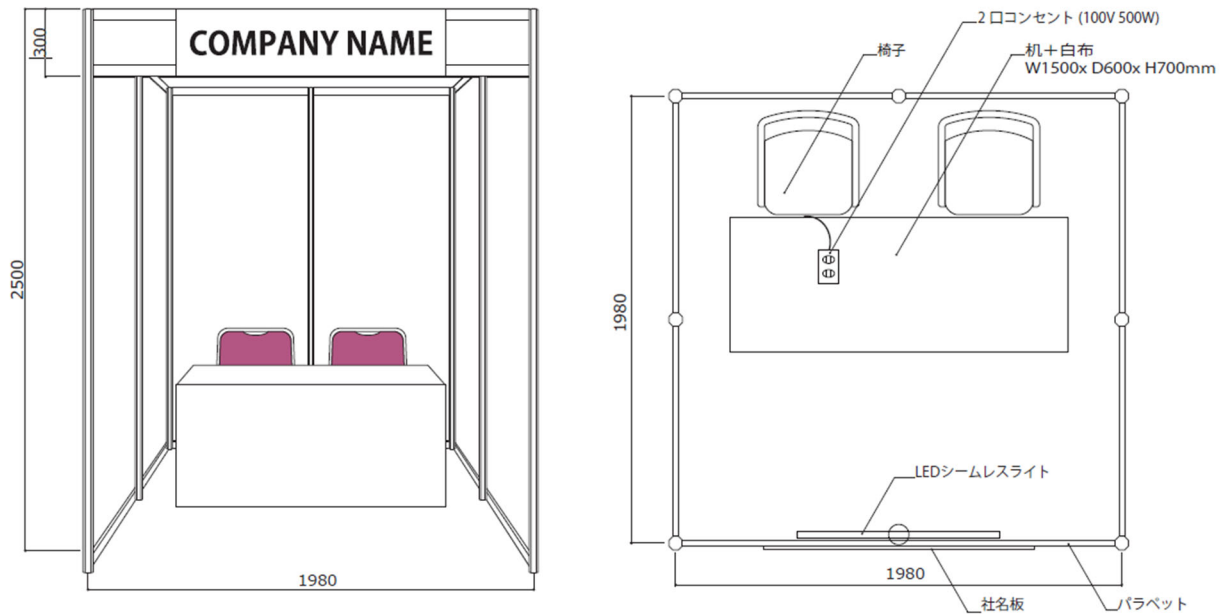
3. About the exhibition

Exhibition Booth Specifications

Size: W1,980mm x D1,980mm x H2,500mm (including back panel)

Standard equipment: 1 long desk (with white cloth), 2 chairs, company name board, 1 fluorescent light, 100V/500W power supply, etc.

Please consult with us in advance if you have any other requests.



The back panel is a white board type.
Thumbtacks and nails cannot be used. Tape can be used.

Booth Image

Exhibition period: May 7 (Tue) 15:00 - May 10 (Fri) 18:00, 2024

	Scheduled date and time
Carrying in	May 7, Tue 15:00 - 18:00
Exhibition	May 8, Wed 9:00 - 17:00
	May 9, Thu 9:00 - 17:00
	May 10, Fri 9:00 - 15:00
Removal	May 10, Fri 15:00 - 17:00

Precautions

- Booth allocation will be decided by the convention steering committee. However, if applications are received by the 2nd call deadline (October 31, 2023), booths can be placed at the desired location in the order of application. Please refer to the following diagram of the booth layout. If the booth you want is already occupied, the secretariat will contact the person in charge in your company to select one of the available booths. Please note that the actual layout may slightly deviate from that shown in the diagram due to aisles and other reasons.
- Exhibition items must be approved by the organizer.
- The height of decorations and exhibits in booths is limited to 2.4m. In principle, direct construction on the floor (duct tape, anchors, etc.) is prohibited.
- Exhibits may not be handed over in exchange for cash during the exhibition.
- The use of water, propane gas, or compressed air is prohibited.
- Exhibitors will be notified of the details of booth allocation, delivery, decoration, management, etc. at least one month prior to the exhibition. Exhibitors will be informed of the leasing of fixtures, lighting fixtures, etc. at this time.
- After the application, exhibitors will be notified of the use of the venue and other precautions for moving in and out of the venue.
- However, we will not be held responsible for accidents, theft, loss, or injury caused by natural disasters or other force majeure, nor will we be liable for the occurrence of human casualties inside the booth.
- The venue, exhibition period, and opening hours may be changed due to unavoidable circumstances. Applications cannot be cancelled due to such changes. No compensation will be provided for any damage caused by such changes.

Exhibit Location

The foyers on the 10th and 12th floors of the Osaka International Convention Center.

Please indicate your preferred booth number on the application form.

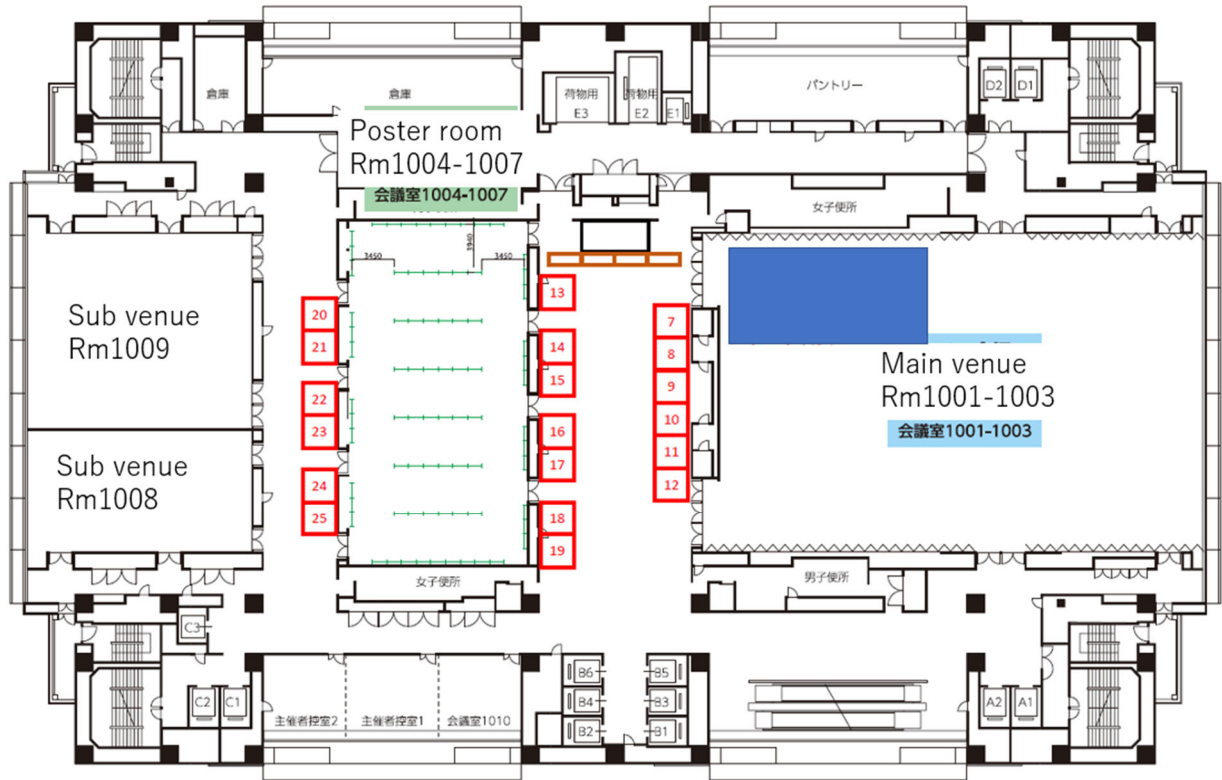


Image: 10F Booth allocation: Booth No 7 to No. 25

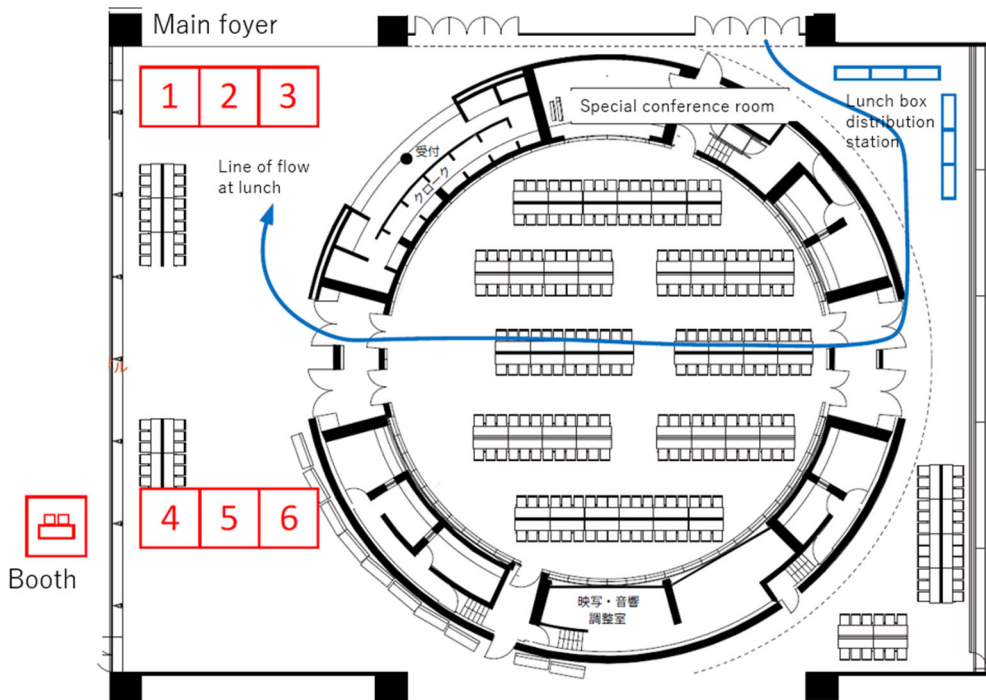


Image: 12F Booth allocation: Booth No. 1 to No. 6

4. Application form

How to apply

Please use the attached application form and send it by e-mail to the following address.

E-mail: sponsor8icege@academicbrains.jp

Contact: Management Office: The 8th International Conference on Earthquake Geotechnical Engineering

Tenmabashi Chiyoda Bldg. 2, 10F, 1-1-1 Ishimachi, Chuo-ku, Osaka 540-0033, Japan

TEL 06-6949-8137 FAX 06-6949-8138

Please note that the name of your company will be used as written on the application form.

Please contact the Management Office as soon as possible in case of any change in the person in charge.

Payment Method

After notification of the decision, the Management Office will issue invoices in due course. Bank transfer charges are to be borne by the applicant.

Cancellation Policy

If you wish to cancel your registration, please contact the Management Office as soon as possible. Please note that cancellation fees will be charged as follows:

After notification of decision: 30% of the total amount of your application

After April 1, 2024 (Monday): 100% of the application amount

Application deadline (2nd call for applications)

Tuesday, October 31 2023

Applications will be accepted on a first-come, first-served basis.

However, if applications are received by the 2nd call deadline (October 31, 2023), booths can be placed at the desired location in the order of application. Please refer to the following diagram of the booth layout. If the booth you want is already occupied, the secretariat will contact the person in charge in your company to select one of the available booths. Please note that the actual layout may slightly deviate from that shown in the diagram due to aisles and other reasons.

E-mail: sponsor8icege@academicbrains.jp

Application Deadline (2nd call for applications) Tuesday, October 31, 2023

The 8th International Conference on Earthquake Engineering and Geotechnical Engineering (8ICEGE) Sponsors

Application for Technical Exhibition

Date of Application _____

Your Company Name*:

Title of the department in charge:

Name of person in charge:

Signature

Address:

Tel & Fax:

Email :

*The name of your company will be used as written on this form

The personal information you provide will be used only for the purpose of providing you with information about the conference and the JGS.

●Application Details (please check in the desired category)

- | | | |
|--------------------------|----------|---------------|
| <input type="checkbox"/> | Platinum | JPY1,000,000* |
| <input type="checkbox"/> | Gold | JPY800,000* |
| <input type="checkbox"/> | Silver | JPY500,000* |
| <input type="checkbox"/> | Bronze | JPY300,000* |
| <input type="checkbox"/> | Sapphire | JPY200,000* |

*10% sales tax will be added

●Booth number (see Page 8) _____

(if applications are received by the first deadline (June 30, 2023), booths can be placed at the desired location in the order of application. If the booth you want is already occupied, the secretariat will contact the person in charge in your company to select one of the available booths. Please note that the actual layout may be slightly different from that shown in the diagram due to aisles, etc.)

●Requests

If you have any requests regarding the exhibition or payment, please fill in the form below.

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●Billing address for sponsorship and exhibition fees

If your contact information is different from the above, please provide your address, department, etc. below.
